Exposure of the inner layers and transfer of the pattern

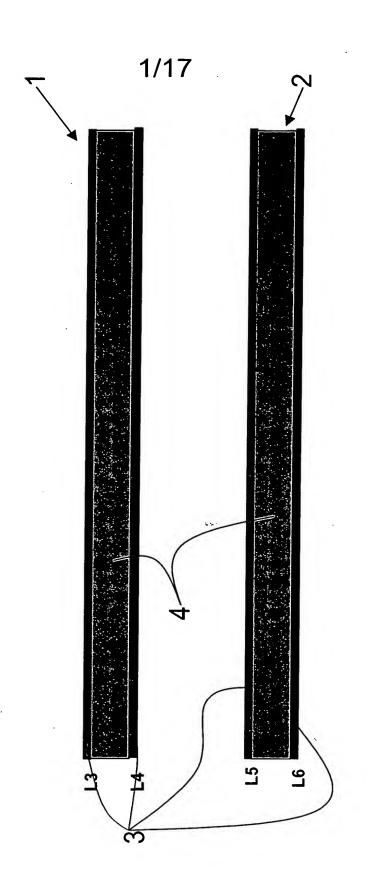
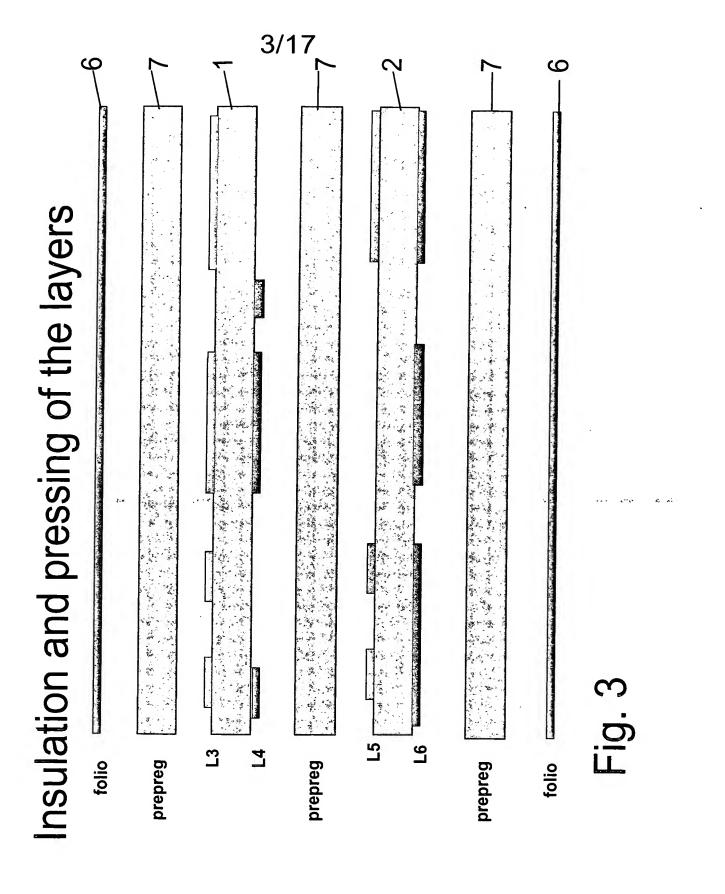
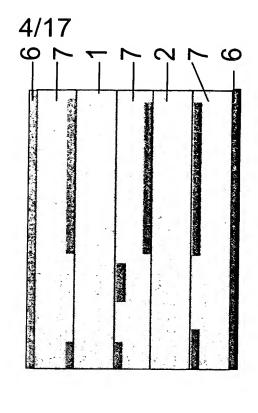


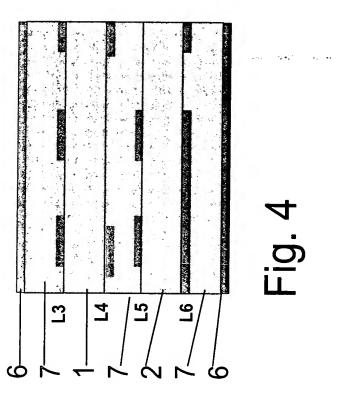
Fig. 1

2/17 Etching of unexposed part and removal of protection



Through-drilling of the inner layers





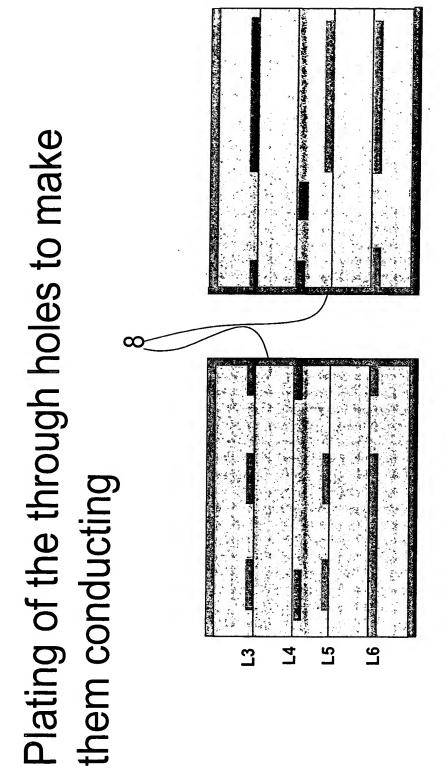
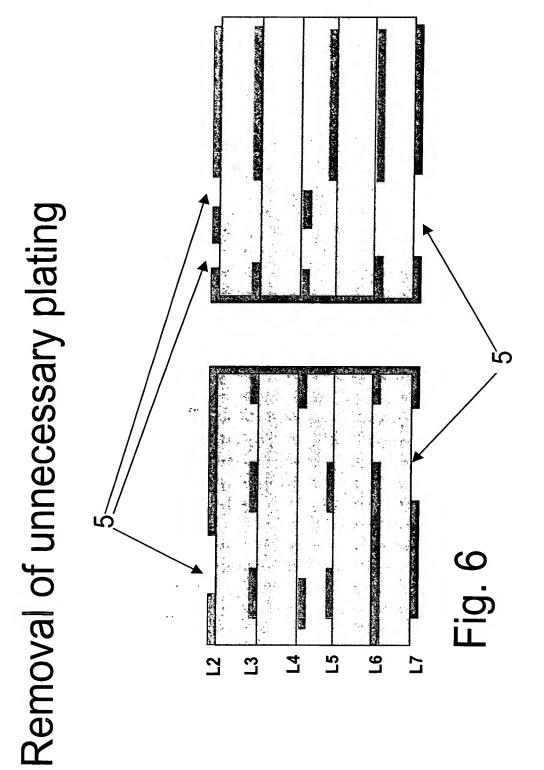


Fig. 5

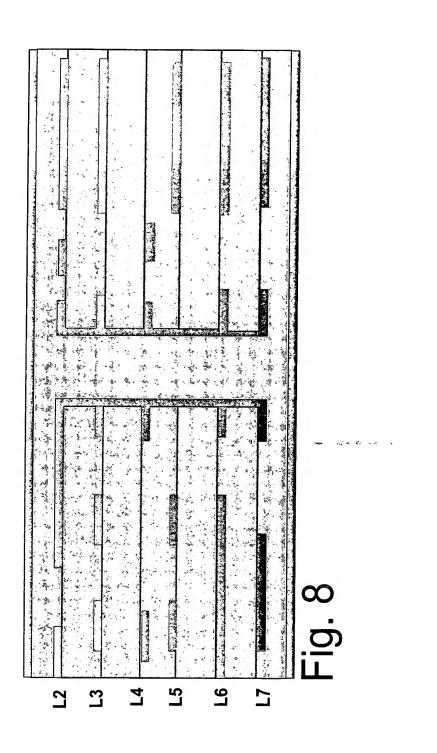
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Formation of the microvia layers, i.e. the outer layers Fig. 7 7 **L**5 97 **L**3 RCC RCC

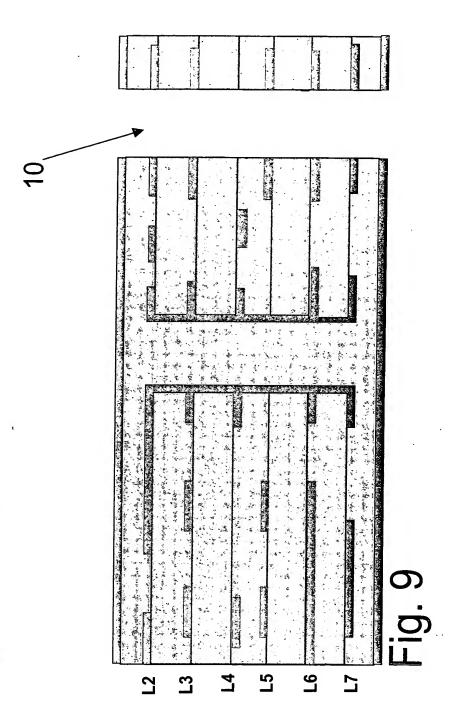
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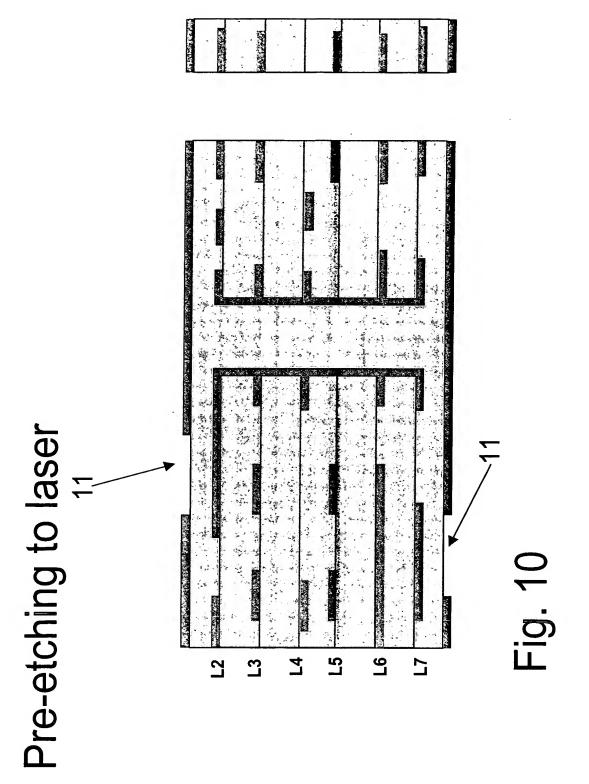
Pressing together



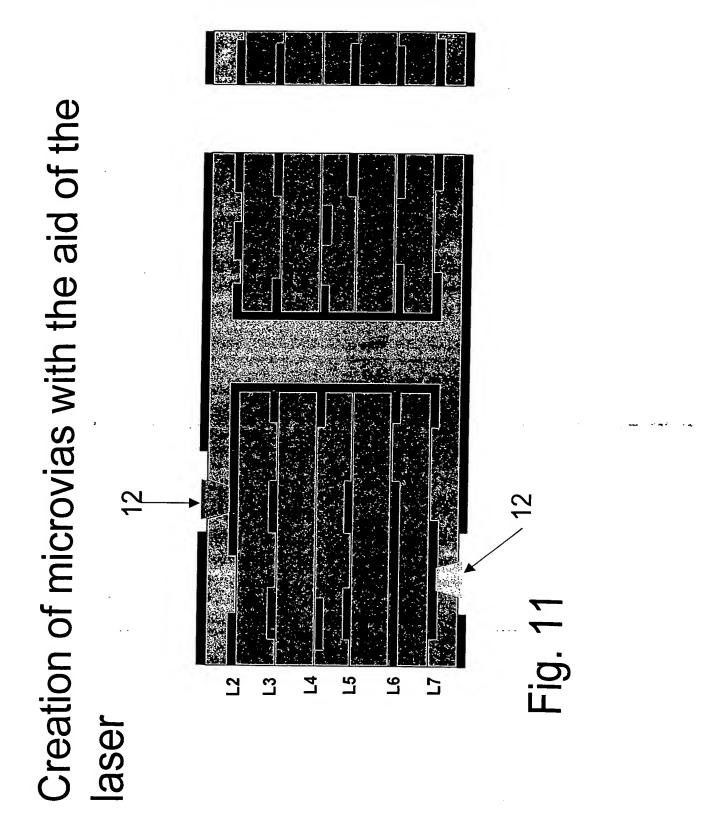


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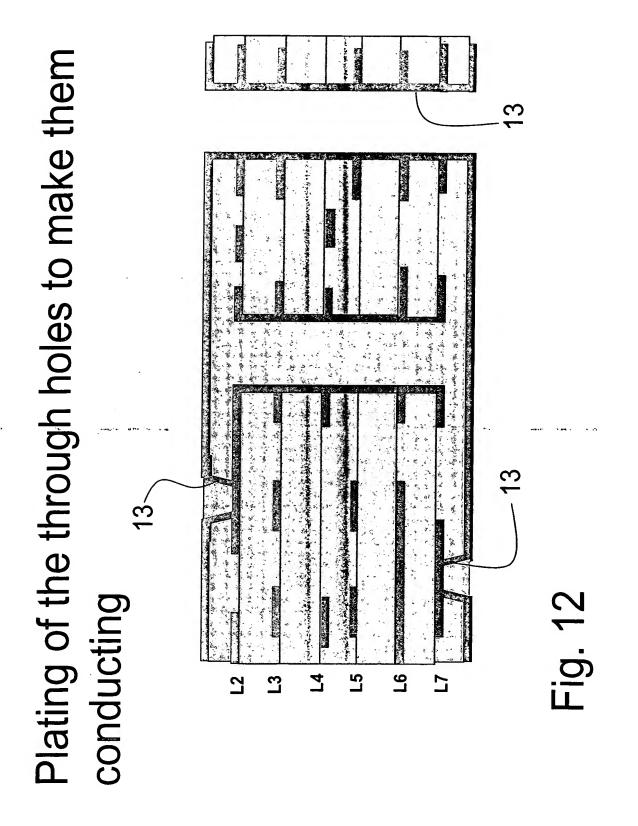


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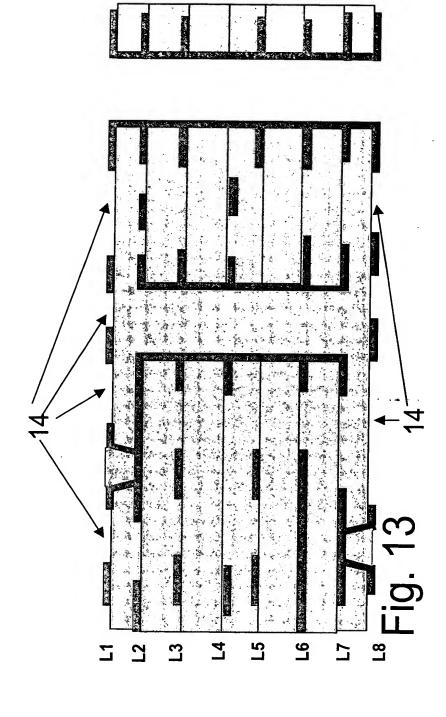


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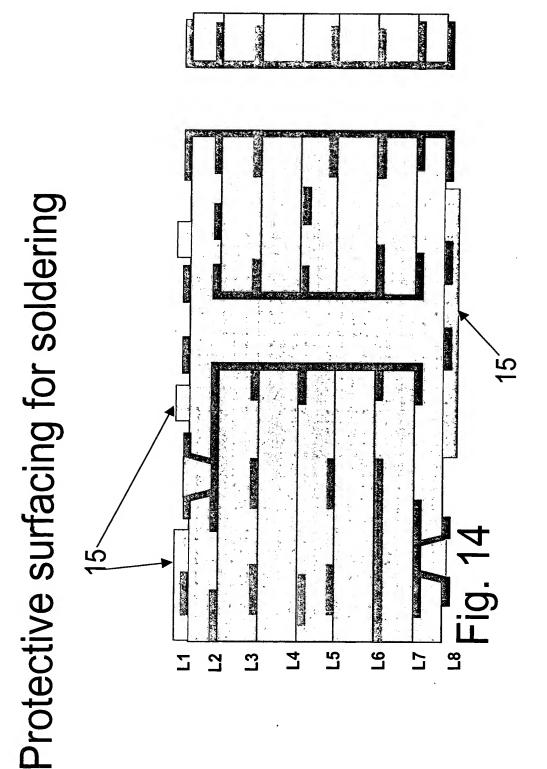


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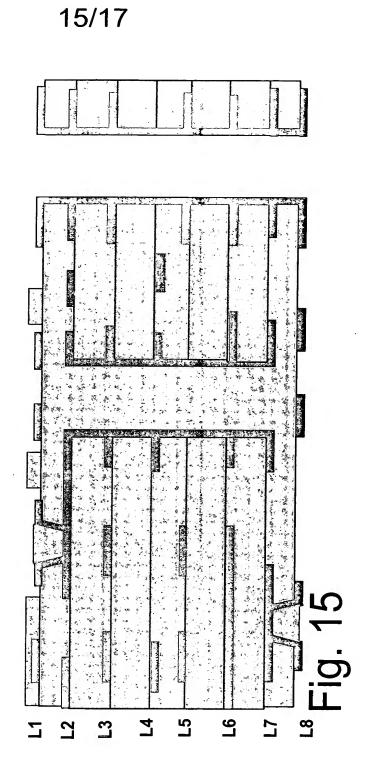


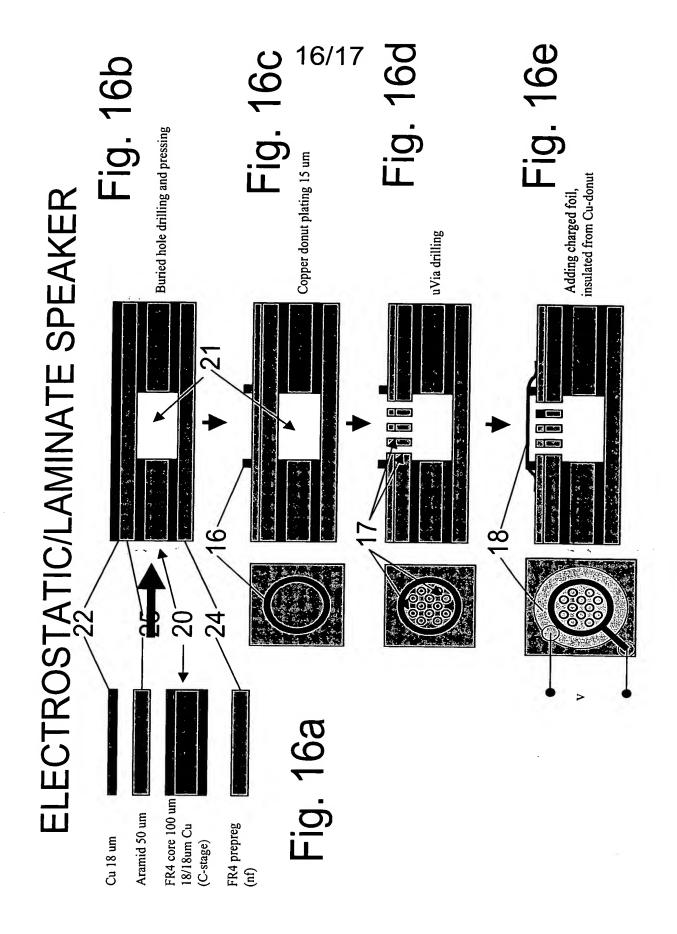
Formation of the conducting pattern

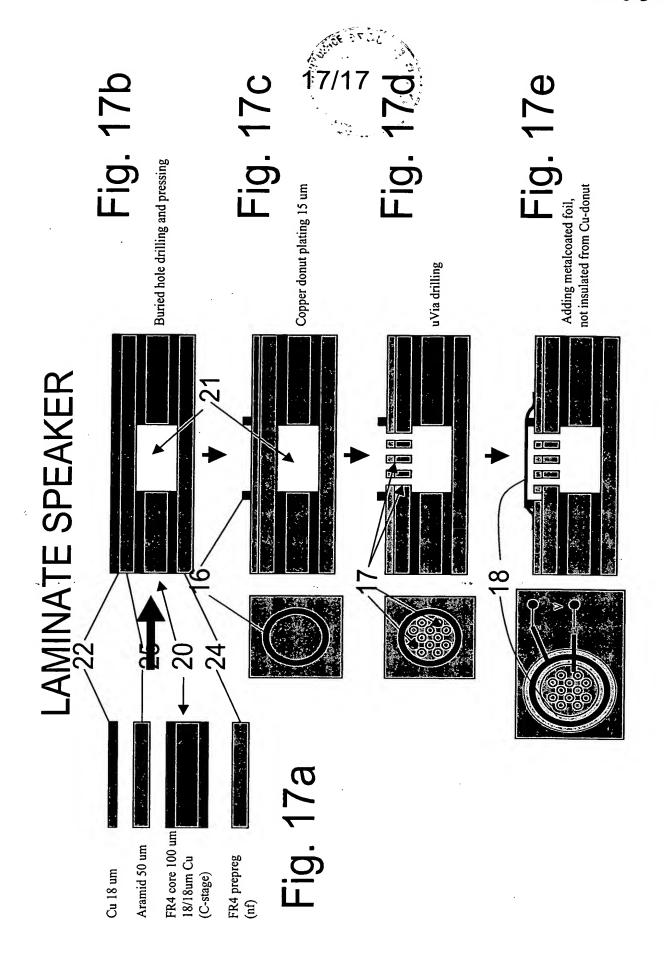
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8-layer microvia plate containing buried through holes







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